

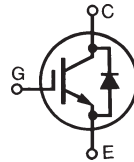
# High Voltage, BiMOSFET™ Monolithic Bipolar MOS Transistor

## IXBF42N300

$$V_{CES} = 3000V$$

$$I_{C110} = 24A$$

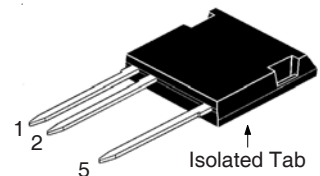
$$V_{CE(sat)} \leq 3.0V$$



(Electrically Isolated Tab)

Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_C = 25^\circ C$ to $150^\circ C$	3000	V
$V_{CGR}$	$T_J = 25^\circ C$ to $150^\circ C$ , $R_{GE} = 1M\Omega$	3000	V
$V_{GES}$	Continuous	$\pm 25$	V
$V_{GEM}$	Transient	$\pm 35$	V
$I_{C25}$	$T_C = 25^\circ C$	60	A
$I_{C110}$	$T_C = 110^\circ C$	24	A
$I_{CM}$	$T_C = 25^\circ C$ , 1ms	380	A
<b>SSOA</b> <b>(RBSOA)</b>	$V_{GE} = 15V$ , $T_{VJ} = 125^\circ C$ , $R_G = 20\Omega$ Clamped Inductive Load	$I_{CM} = 84$ $V_{CE} \leq 0.8 \cdot V_{CES}$	A
$T_{SC}$ <b>(SCSOA)</b>	$V_{GE} = 15V$ , $T_J = 125^\circ C$ , $R_G = 82\Omega$ , $V_{CE} = 1500V$ , Non-Repetitive	10	$\mu s$
$P_C$	$T_C = 25^\circ C$	240	W
$T_J$		-55 ... +150	$^\circ C$
$T_{JM}$		150	$^\circ C$
$T_{stg}$		-55 ... +150	$^\circ C$
$T_L$	1.6mm (0.062 in.) from Case for 10s	300	$^\circ C$
$T_{SOLD}$	Plastic Body for 10 seconds	260	$^\circ C$
$F_C$	Mounting Force	20..120 / 4.5..27	Nm/lb.in.
$V_{ISOL}$	50/60Hz, 1 Minute	3000	V~
<b>Weight</b>		5	g

### ISOPLUS i4-Pak™



1 = Gate  
2 = Emitter

5 = Collector

### Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 3000V~ Electrical Isolation
- High Blocking Voltage
- High Peak Current Capability
- Low Saturation Voltage
- FBSOA Rated
- SCSOA Rated

### Advantages

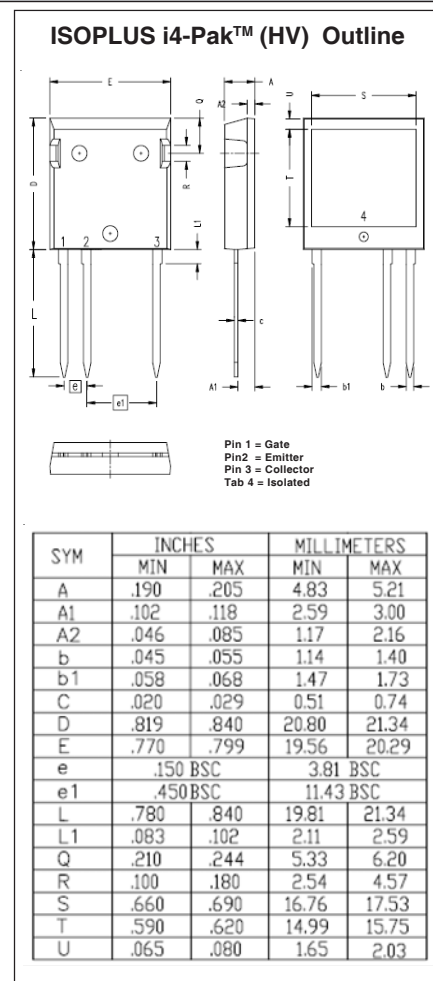
- Low Gate Drive Requirement
- High Power Density

### Applications

- Laser Generators
- Capacitor Discharge Circuits
- AC Switches
- Protection Circuits

Symbol	Test Conditions ( $T_J = 25^\circ C$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{CES}$	$I_C = 1mA$ , $V_{GE} = 0V$	3000		V
$V_{GE(th)}$	$I_C = 1mA$ , $V_{CE} = V_{GE}$	3.0		5.0 V
$I_{CES}$	$V_{CE} = 0.8 \cdot V_{CES}$ , $V_{GE} = 0V$ Note 2, $T_J = 125^\circ C$		250	50 $\mu A$ 50 $\mu A$
$I_{GES}$	$V_{CE} = 0V$ , $V_{GE} = \pm 25V$			$\pm 200$ nA
$V_{CE(sat)}$	$I_C = 42A$ , $V_{GE} = 15V$ , Note 1 $T_J = 125^\circ C$		2.5 3.1	3.0 V V

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$I_C = 42\text{A}, V_{CE} = 10\text{V}$ , Note 1	28	45	S
$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		4780	pF
$C_{oes}$			170	pF
$C_{res}$			56	pF
$R_{Gi}$	Gate Input Resistance		3.0	$\Omega$
$Q_g$	$I_C = 42\text{A}, V_{GE} = 15\text{V}, V_{CE} = 1000\text{V}$		200	nC
$Q_{ge}$			28	nC
$Q_{gc}$			75	nC
$t_{d(on)}$	<b>Resistive Switching Times, <math>T_J = 25^\circ\text{C}</math></b> $I_C = 42, V_{GE} = 15\text{V}$ $V_{CE} = 1500\text{V}, R_G = 20\Omega$		72	ns
$t_r$			330	ns
$t_{d(off)}$			445	ns
$t_f$			610	ns
$t_{d(on)}$	<b>Resistive Switching Times, <math>T_J = 125^\circ\text{C}</math></b> $I_C = 42, V_{GE} = 15\text{V}$ $V_{CE} = 1500\text{V}, R_G = 20\Omega$		72	ns
$t_r$			580	ns
$t_{d(off)}$			460	ns
$t_f$			490	ns
$R_{thJC}$				0.52 $^\circ\text{C/W}$
$R_{thCS}$		0.15		$^\circ\text{C/W}$



## Reverse Diode

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
$V_F$	$I_F = 42\text{A}, V_{GE} = 0\text{V}$ , Note 1			2.5 V
$t_{rr}$	$I_F = 21\text{A}, V_{GE} = 0\text{V}, -di_F/dt = 100\text{A}/\mu\text{s}$		1.7	$\mu\text{s}$
$I_{RM}$		$V_R = 100\text{V}, V_{GE} = 0\text{V}$		43

## Notes:

1. Pulse test,  $t < 300\mu\text{s}$ , duty cycle,  $d < 2\%$ .
2. Device must be heatsunk for high-temperature leakage current measurements to avoid thermal runaway.

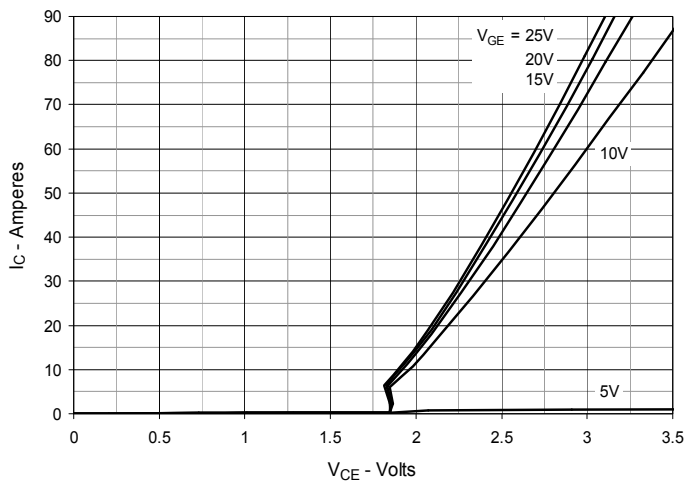
### PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

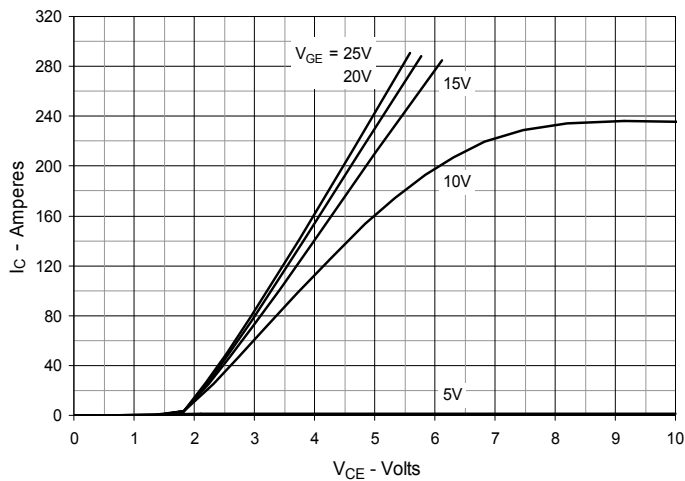
IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

IXYS MOSFETs and IGBTs are covered 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2  
by one or more of the following U.S. patents: 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2  
4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

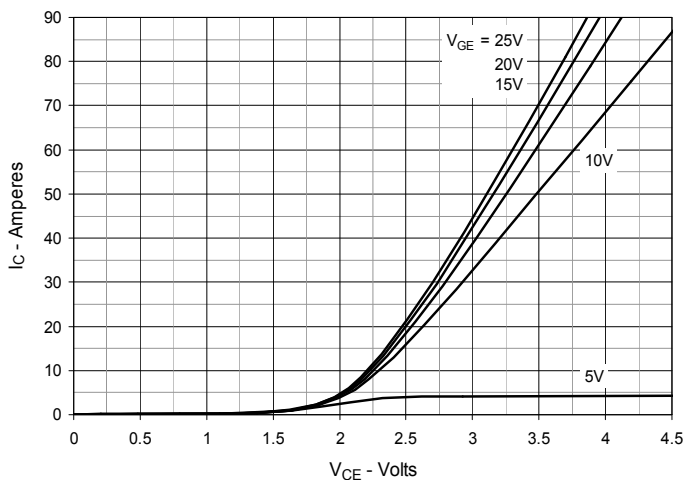
**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$**



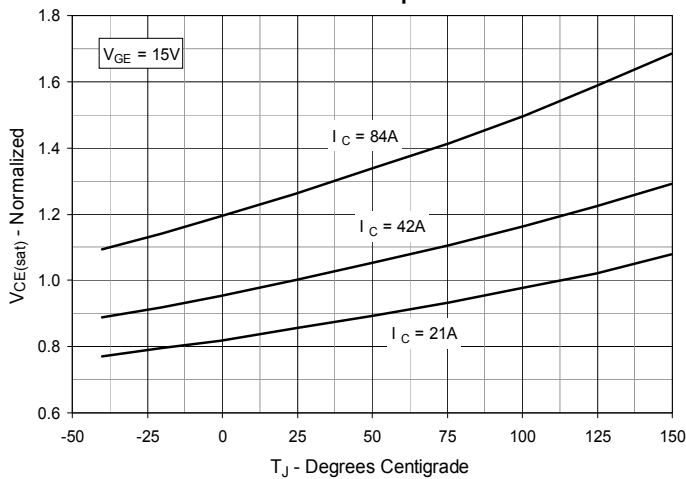
**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$**



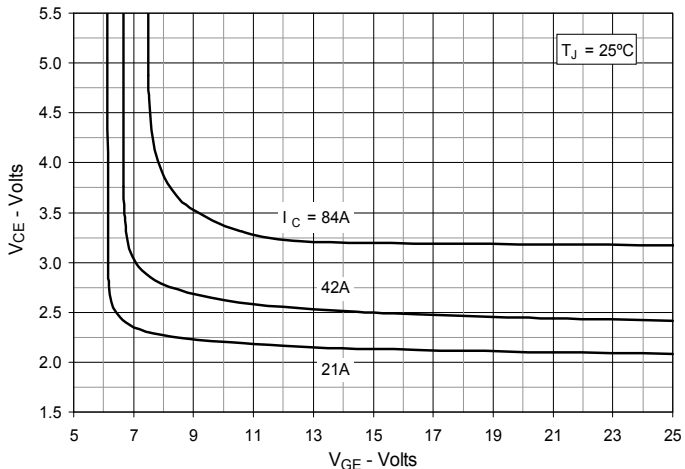
**Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$**



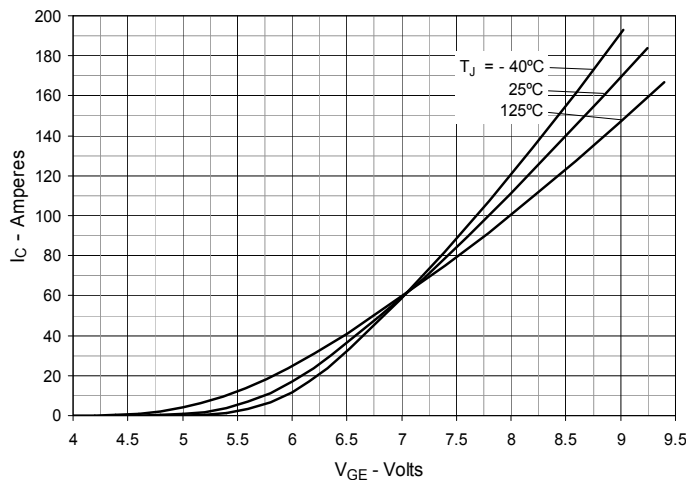
**Fig. 4. Dependence of  $V_{CE(sat)}$  on Junction Temperature**

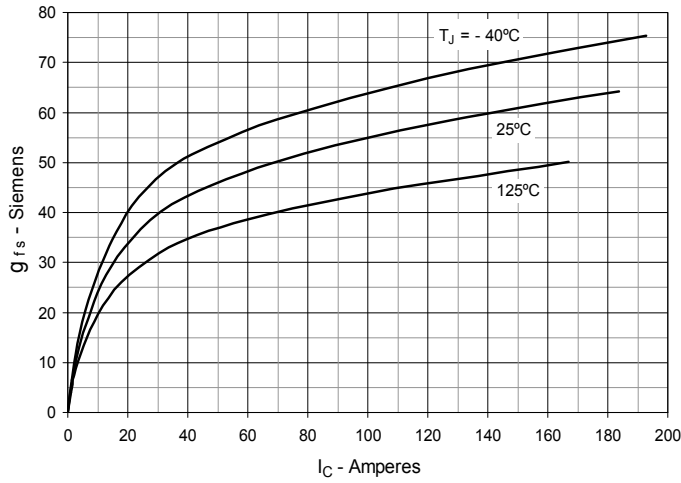
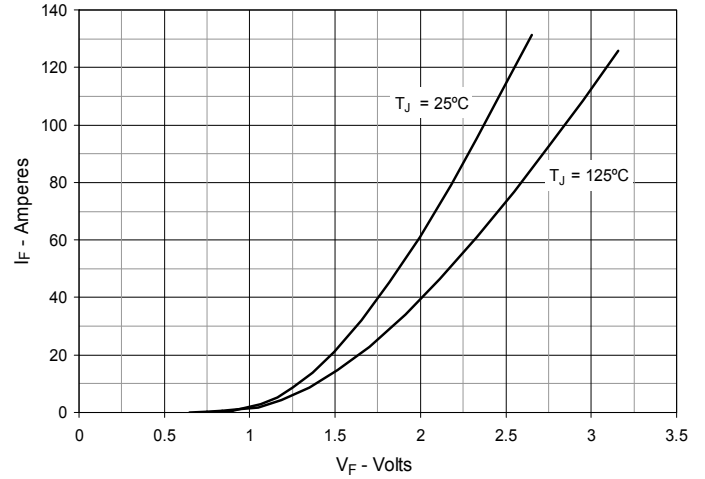
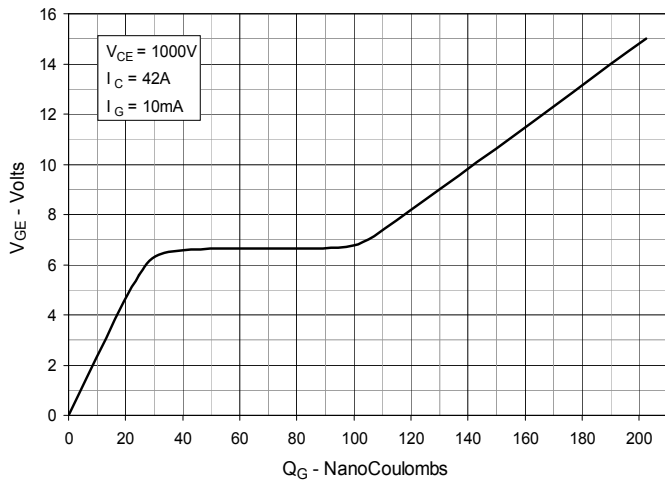
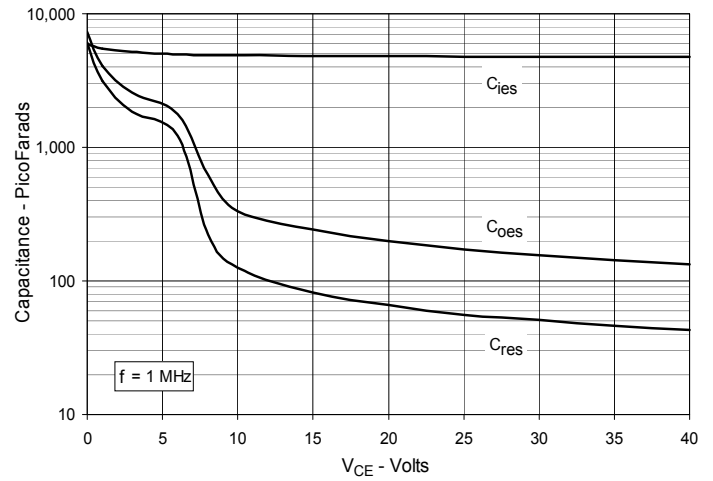
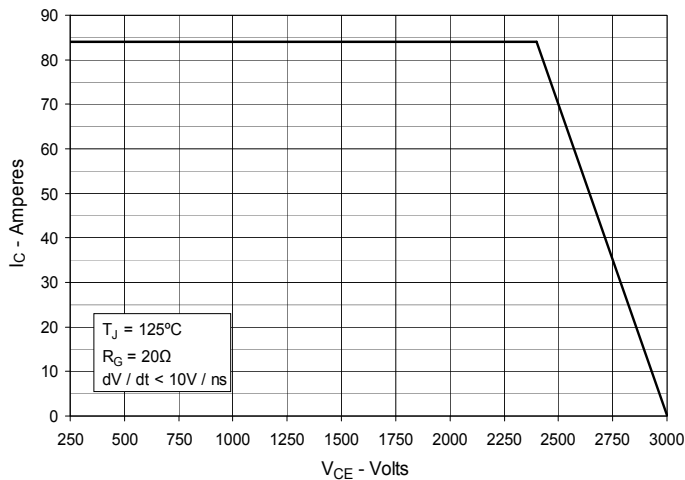
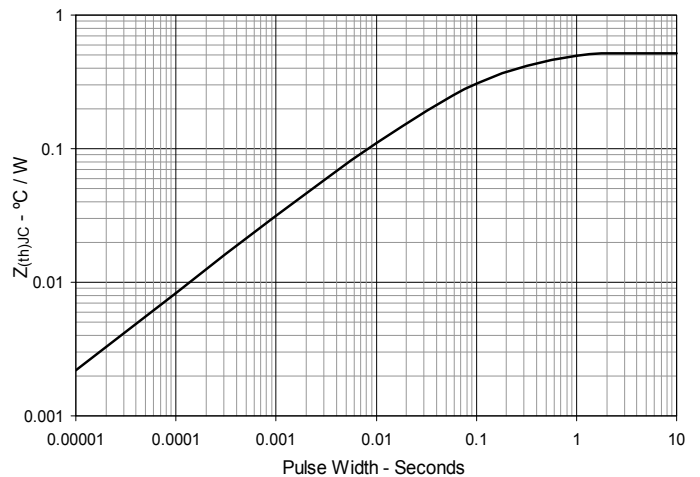


**Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage**



**Fig. 6. Input Admittance**



**Fig. 7. Transconductance**

**Fig. 8. Forward Voltage Drop of Intrinsic Diode**

**Fig. 9. Gate Charge**

**Fig. 10. Capacitance**

**Fig. 11. Reverse-Bias Safe Operating Area**

**Fig. 12. Maximum Transient Thermal Impedance**


IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

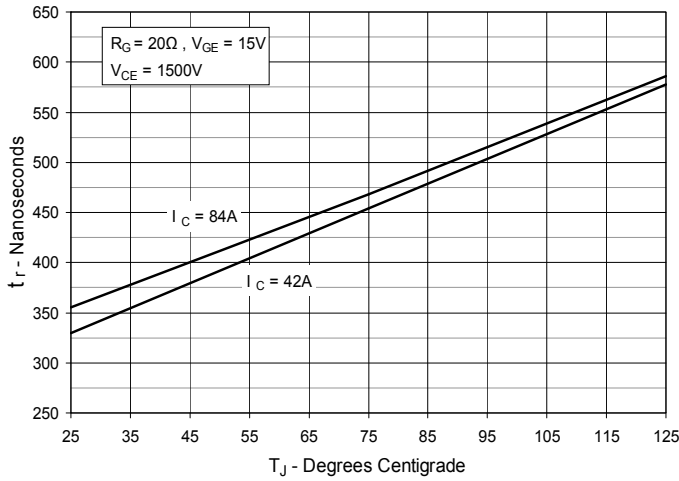


Fig. 14. Resistive Turn-on Rise Time vs. Collector Current

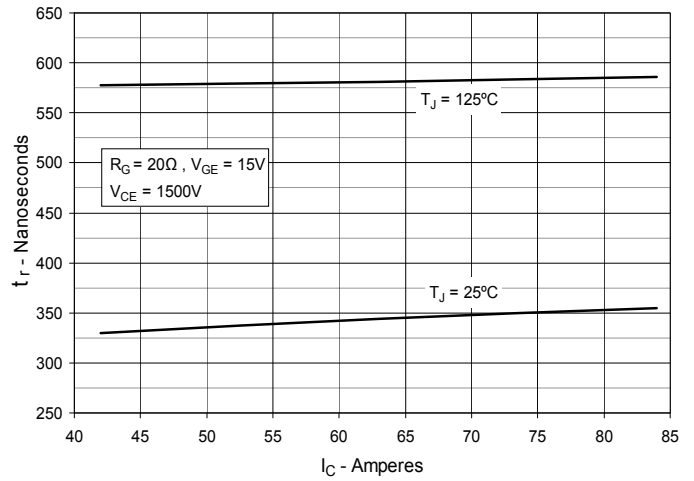


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

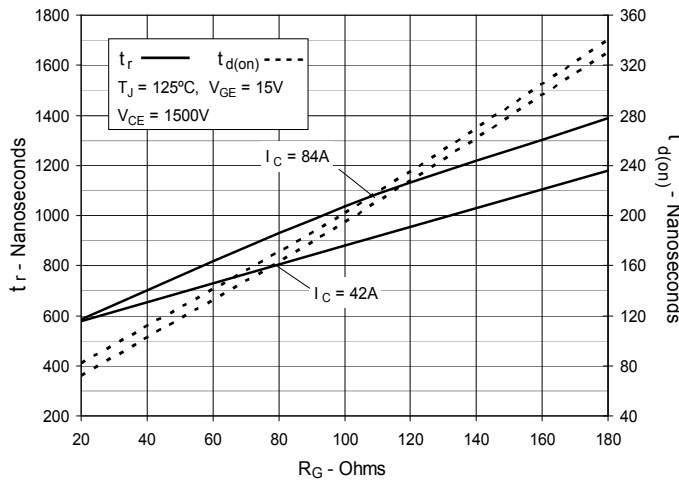


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

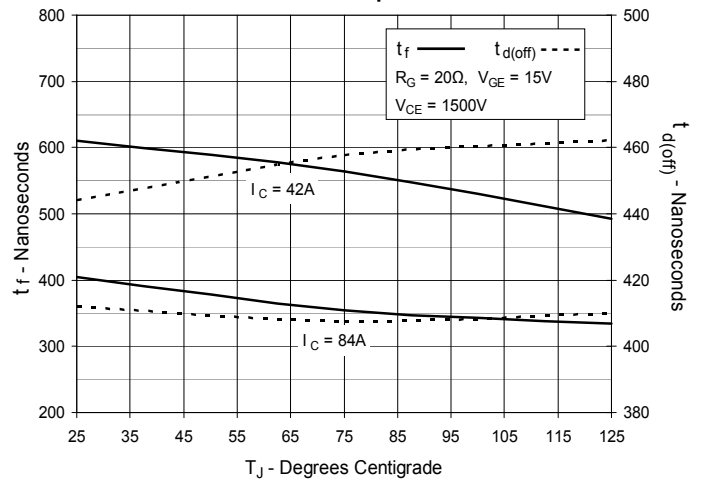


Fig. 17. Resistive Turn-off Switching Times vs. Collector Current

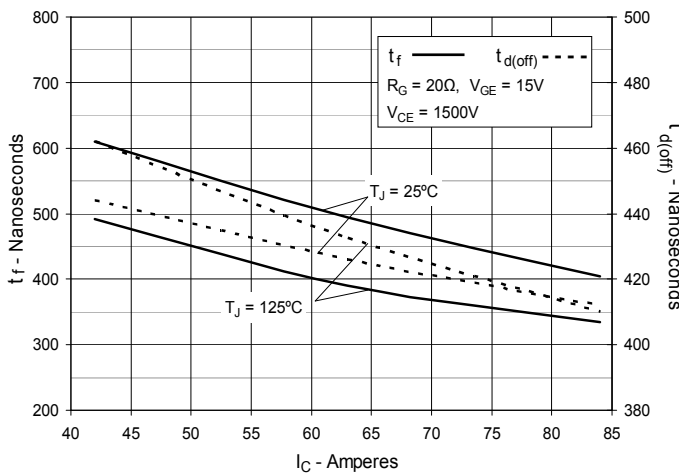
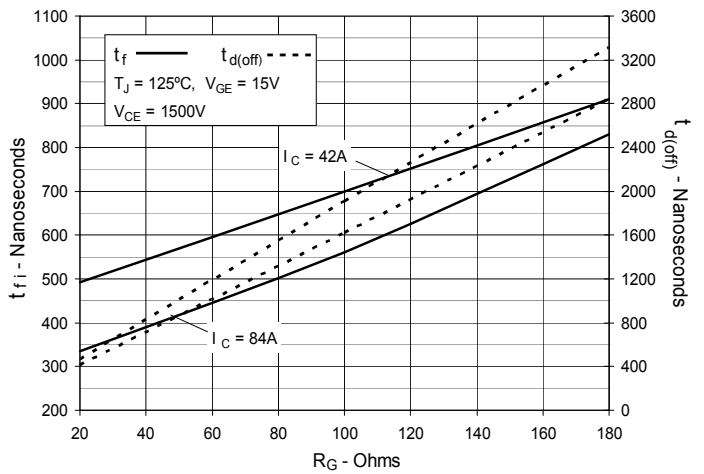
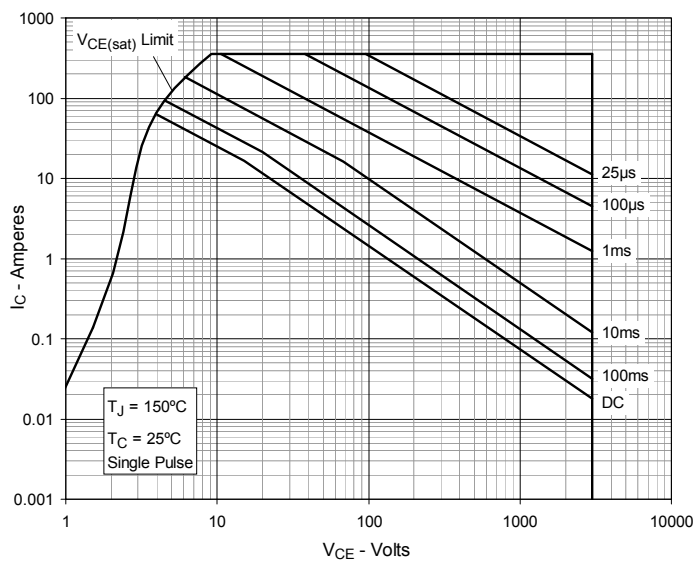


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance



**Fig. 19. Forward-Bias Safe Operating Area @  $T_C = 25^\circ\text{C}$**



**Fig. 20. Forward-Bias Safe Operating Area @  $T_C = 115^\circ\text{C}$**

